

Product / Process Change Notice

Parts Affected:

The following NPN power transistors:

Part Numbers Affected:

CEN1323

CEN667

CEN709

2N3773

2N4348

2N6259

Extent of Change:

Change in wafer fab, resulting in change in die size from 217 x 217 mils to 201 x 201 mils.

Reason for Change:

As part of Central Semiconductor's supply chain risk mitigation initiative, and in an effort to ensure an uninterrupted supply of product, a change in wafer fabrication site is being made for the products referenced above. Product specifications, quality and reliability are not impacted by this change.

Effect of Change:

This change does not affect electrical device characteristics.

Earliest Effective Date of Change:

August 20, 2021

Inventory Availability

Existing inventory will be shipped until depleted.

PCN #220
Notification Date:
June 2, 2021

Qualification:

Test	Condition	Duration	Failure rate
High Temperature Storage Life	Ta=150°C	1000 Hours	0/77
Thermal Shock	dwel time = 5 min, -65°C to +150°C, max transfer time = 20 sec.	100 Cycles	0/77
High Temperature Reverse Bias	Ta=125°C, Bias conditions per device datasheet.	1000 Hours	0/77
Solderability	Steam Age: T=93°C +3/-5°C. Non Pb-free Dip: T=215°C +/-5°C, Pb-free Dip: T=245°C +/-5°C, Dwell time = 5+/-0.5sec	1 Cycle	0/15
Temperature Cycling	Dwell time = 15 min Ta = -65°C to +150°C Transfer time less than 1min.	1000 Cycles	0/77

Sample Availability:

Please contact your salesperson or manufacturer's representative for samples.

As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor's Product/Process Change Notification (PCN).

Company Name:	
Address:	
Printed Name:	
Title:	
Signature:	
Date:	